



## **Statement regarding High Temperature Melting Solder Application**

--Specific to RoHS Exemption Clause 7 (a) and ELV Exemption Clause 8(e)--

After more than a decade of substantial development efforts in the power semiconductor industry, today's lead-free solder material technologies for die attach / clip bonding application are not ready to substitute leaded high melting temperature solders as a drop-in solution. While AOS is committed to continuously working on the drop-in solution for leaded high temperature solders, and closely working with material suppliers and equipment suppliers, no single drop-in lead-free solder is in near sight.

Based on the current status, AOS cannot predict a date for replacing leaded solder with leaded-free solder. The release process will take a substantial amount of time, and AOS will post the update when more solid results are available.

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<b>Declaration</b>
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